

ME6874-VB Datasheet Dual N-Channel 20 V (D-S) MOSFET

PRODUCT SUMMARY							
V _{DS} (V)	$R_{DS(on)}(\Omega)$	I _D (A) ^a	Q _g (Typ.)				
20	0.022 at V _{GS} = 4.5 V	6.0	1.8 nC				
	0.028 at V _{GS} = 2.5 V	5.0	1.0110				

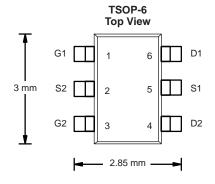
FEATURES

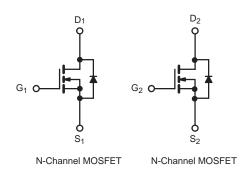
 Halogen-free According to IEC 61249-2-21 Definition



RoHS

- Trench Power MOSFET
- 100 % R_g Tested
- Compliant to RoHS Directive 2002/95/EC





ABSOLUTE MAXIMUM RATIN	GS $I_A = 25^{\circ}C$,			
Parameter	Symbol	Limit	Unit	
Drain-Source Voltage	V_{DS}	20	V	
Gate-Source Voltage	V_{GS}	± 12	V	
	T _C = 25 °C		6.0	
Continuous Drain Current (T _{.1} = 150 °C)	$T_C = 70 ^{\circ}C$	I _D	4.0	
Continuodo Brain Carrent (1) = 100 °C)	T _A = 25 °C	טי	3.5 ^{b, c}	
	T _A = 70 °C		2.8 ^{b, c}	A
Pulsed Drain Current		I _{DM}	18	
	T _C = 25 °C		1.17	
Continuous Source-Drain Diode Current	T _A = 25 °C	I _S	0.95 ^{b, c}	
	T _C = 25 °C		1.6	
Maximum Power Dissipation	T _C = 70 °C	P _D	1.0	w
Maximum rower bissipation	T _A = 25 °C	٠,٥	1.14 ^{b, c}	• • • • • • • • • • • • • • • • • • • •
	T _A = 70 °C		0.73 ^{b, c}	
Operating Junction and Storage Temperature	T _J , T _{stg}	- 55 to 150	°C	
Soldering Recommendations (Peak Tempera		260		

THERMAL RESISTANCE RATINGS							
Parameter	Symbol	Typical	Maximum	Unit			
Maximum Junction-to-Ambient ^{b, d}	t ≤ 5 s	R_{thJA}	93	110	°C/W		
Maximum Junction-to-Foot	Steady State	R_{thJF}	75	90	S/ V V		

Notes:

- a. $T_C = 25$ °C.
- b. Surface Mounted on 1" x 1" FR4 board.
- c. t = 5 s
- d. Maximum under steady state conditions is 150 °C/W.



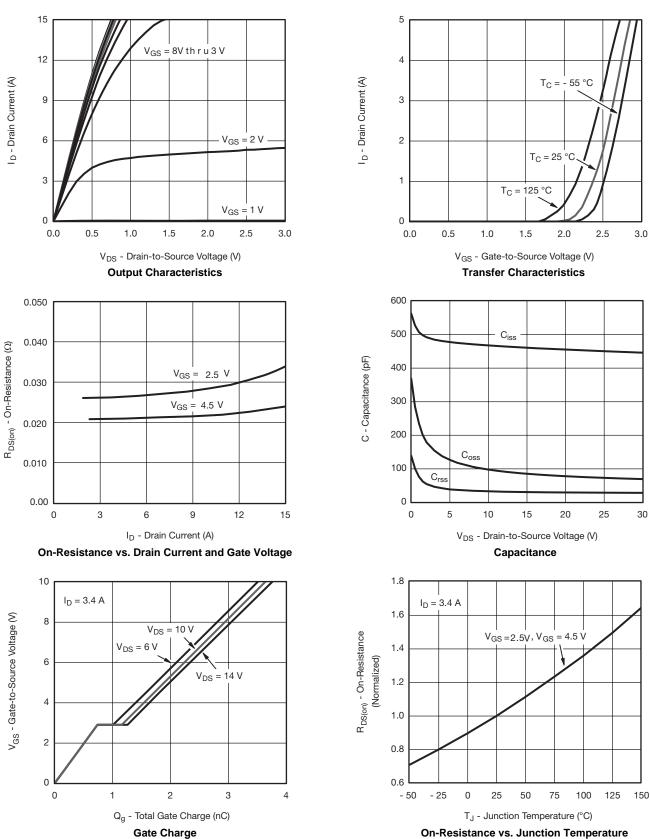
Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit
Static			L			
Drain-Source Breakdown Voltage	V _{DS}	$V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$	20			V
V _{DS} Temperature Coefficient	$\Delta V_{DS}/T_{J}$	s/T		29		1400
V _{GS(th)} Temperature Coefficient	$\Delta V_{GS(th)}/T_J$	I _D = 250 μA		- 4		mV/°C
Gate-Source Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}$, $I_{D} = 250 \mu A$	0.4		1.5	V
Gate-Source Leakage	I _{GSS}	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$			± 100	nA
7 0	1.	$V_{DS} = 20 \text{ V}, V_{GS} = 0 \text{ V}$			1	μA
Zero Gate Voltage Drain Current	IDSS	V _{DS} = 20 V, V _{GS} = 0 V, T _J = 55 °C			10	
On-State Drain Current ^a	I _{D(on)}	$V_{DS} \ge 5 \text{ V}, V_{GS} = 10 \text{ V}$	10			Α
		$V_{GS} = 4.5 \text{ V}, I_D = 3.4 \text{ A}$		0.022		Ω
Drain-Source On-State Resistance ^a	R _{DS(on)}	$V_{GS} = 2.5 \text{ V}, I_D = 3.0 \text{ A}$		0.028		
Forward Transconductance ^a	9 _{fs}	V _{DS} = 10 V, I _D = 3.4 A		10		S
Dynamic ^b						
Input Capacitance	C _{iss}			400		
Output Capacitance	C _{oss}	$V_{DS} = 10 \text{ V}, V_{GS} = 0 \text{ V}, f = 1 \text{ MHz}$		55		pF
Reverse Transfer Capacitance	C _{rss}			26		
Total Gate Charge	Q _g	$V_{DS} = 10 \text{ V}, V_{GS} = 10 \text{ V}, I_{D} = 3.4 \text{ A}$		3.7	6	nC
				1.8	3	
Gate-Source Charge	Q _{gs}	$V_{DS} = 10 \text{ V}, V_{GS} = 4.5 \text{ V}, I_D = 3.4 \text{ A}$		0.74		
Gate-Drain Charge	Q _{gd}			0.42		
Gate Resistance	R _g	f = 1 MHz	1	5	10	Ω
Turn-On Delay Time	t _{d(on)}			10	20	ns
Rise Time	t _r	V_{DD} = 10 V, R_L = 5.6 Ω		15	30	
Turn-Off Delay Time	t _{d(off)}	$I_D\cong 2.7~A,~V_{GEN}=4.5~V,~R_g=1~\Omega$		10	20	
Fall Time	t _f			10	20	
Turn-On Delay Time	t _{d(on)}			5	10	
Rise Time	t _r	V_{DD} = 10 V, R_L = 5.6 Ω		15	30	
Turn-Off Delay Time	t _{d(off)}	$I_D\cong$ 2.7 A, V_{GEN} = 10 V, R_g = 1 Ω		10	20	
Fall Time	t _f			10	20	
Drain-Source Body Diode Characteristi	cs					
Continuous Source-Drain Diode Current	I _S	T _C = 25 °C		1.2		Λ
Pulse Diode Forward Current	I _{SM}			18		A
Body Diode Voltage	V_{SD}	$I_S = 2.7 \text{ A}, V_{GS} = 0 \text{ V}$		0.85	1.2	V
Body Diode Reverse Recovery Time	t _{rr}			10	20	ns
Body Diode Reverse Recovery Charge	Q _{rr}	L_ = 2.7 A dl/dt = 100 A/vo T = 25 °C		4	10	nC
Reverse Recovery Fall Time	t _a	$I_F = 2.7 \text{ A}, \text{ dI/dt} = 100 \text{ A/}\mu\text{s}, T_J = 25 ^{\circ}\text{C}$		6		
Reverse Recovery Rise Time	t _b	t _b		4		ns

Notes:

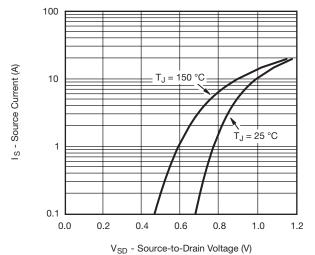
- a. Pulse test; pulse width $\leq 300~\mu s,$ duty cycle $\leq 2~\%$
- b. Guaranteed by design, not subject to production testing.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

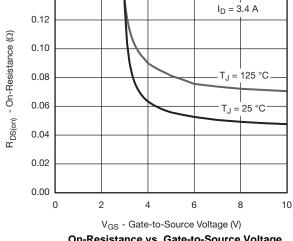






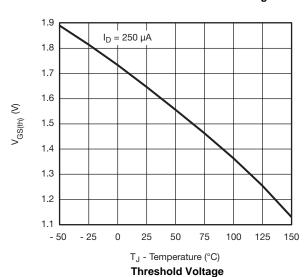


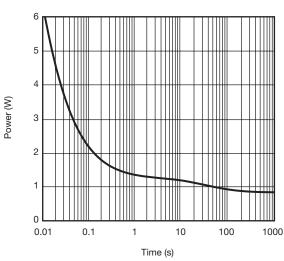
Source-Drain Diode Forward Voltage



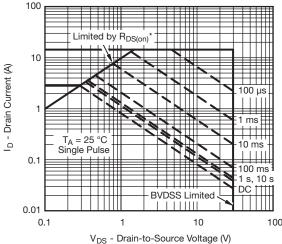
0.14

On-Resistance vs. Gate-to-Source Voltage





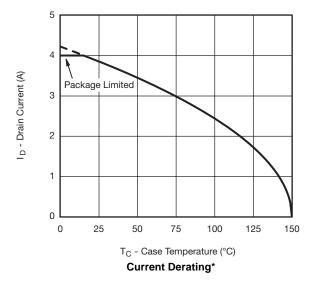
Single Pulse Power (Junction-to-Ambient)

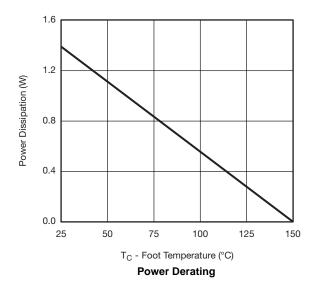


 * V $_{GS}$ > minimum V $_{GS}$ at which R $_{DS(on)}$ is specified

Safe Operating Area, Junction-to-Ambient

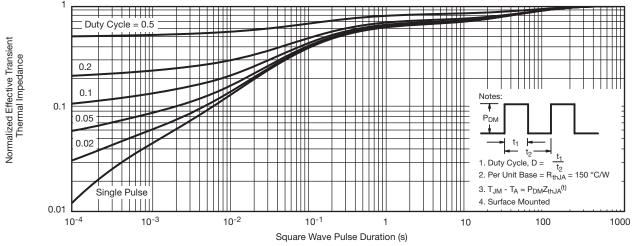




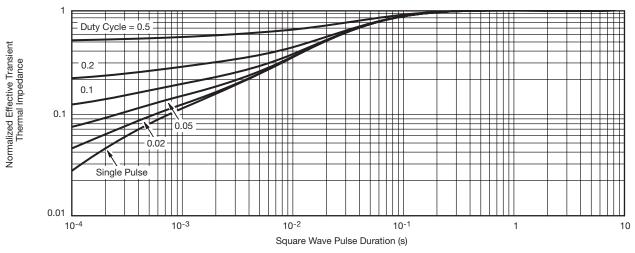


^{*} The power dissipation P_D is based on $T_{J(max)} = 150$ °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit.





Normalized Thermal Transient Impedance, Junction-to-Ambient

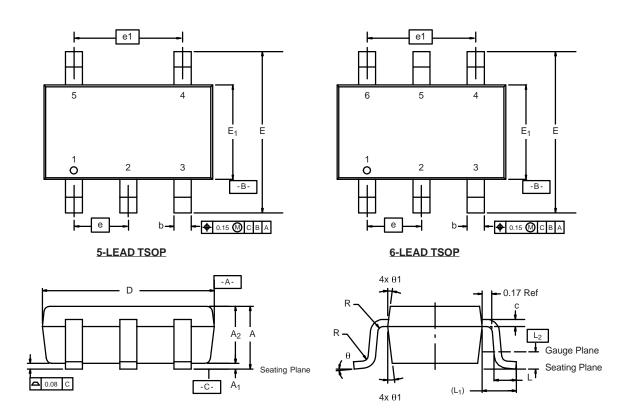


Normalized Thermal Transient Impedance, Junction-to-Foot



TSOP: 5/6-LEAD

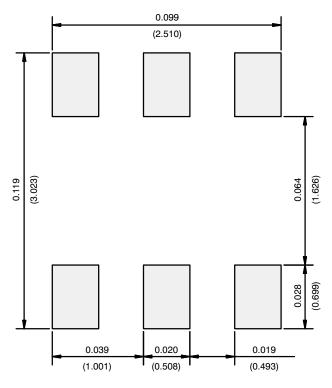
JEDEC Part Number: MO-193C



	MILLIMETERS			INCHES			
Dim	Min	Nom	Max	Min	Nom	Max	
Α	0.91	-	1.10	0.036	-	0.043	
A ₁	0.01	-	0.10	0.0004	-	0.004	
A ₂	0.90	-	1.00	0.035	0.038	0.039	
b	0.30	0.32	0.45	0.012	0.013	0.018	
С	0.10	0.15	0.20	0.004	0.006	0.008	
D	2.95	3.05	3.10	0.116	0.120	0.122	
Е	2.70	2.85	2.98	0.106	0.112	0.117	
E ₁	1.55	1.65	1.70	0.061	0.065	0.067	
е	0.95 BSC			0.0374 BSC			
e ₁	1.80	1.90	2.00	0.071	0.075	0.079	
L	0.32	-	0.50	0.012	-	0.020	
L ₁	0.60 Ref			0.024 Ref			
L ₂	0.25 BSC			0.010 BSC			
R	0.10	-	-	0.004	-	-	
θ	0°	4°	8°	0°	4°	8°	
θ ₁	7° Nom			7° Nom			
ECN: C-06593-Rev. I, 18-Dec-06 DWG: 5540							



RECOMMENDED MINIMUM PADS FOR TSOP-6



Recommended Minimum Pads Dimensions in Inches/(mm)



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